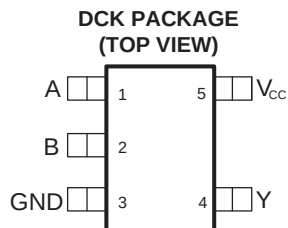


Low-Power Single 2-Input Positive-AND Gate

Check for Samples: [SN74AUP1G08-Q1](#)

FEATURES

- AEC-Q100 Qualified with the Following Results:
 - Device Temperature Grade 1: –40°C to 125°C Ambient Operating Temperature Range
 - Device HBM ESD Classification Level H2
 - Device CDM ESD Classification Level C3B
- Available in the Texas Instruments NanoStar™ Package
- Low Static-Power Consumption:
 $I_{CC} = 0.9 \mu A$ Max
- Low Dynamic-Power Consumption:
 $C_{pd} = 4.3$ pF Typ at 3.3 V
- Low Input Capacitance: $C_i = 1.5$ pF Typ
- Low Noise: Overshoot and Undershoot < 10% of V_{CC}
- I_{off} Supports Partial-Power-Down Mode Operation
- Schmitt-Trigger Action Allows Slow Input Transition and Better Switching Noise Immunity at the Input ($V_{hys} = 250$ mV, Typ at 3.3 V)
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V Input/Output (I/O) Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 4.3$ ns Max at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD-78, Class II



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2012, Texas Instruments Incorporated

DESCRIPTION

The AUP family is TI's premier solution to the low-power needs of the industry in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in increased battery life (see Figure 1). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in Figure 2).

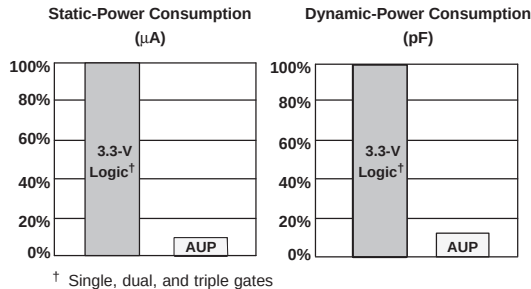


Figure 1. AUP – The Lowest-Power Family

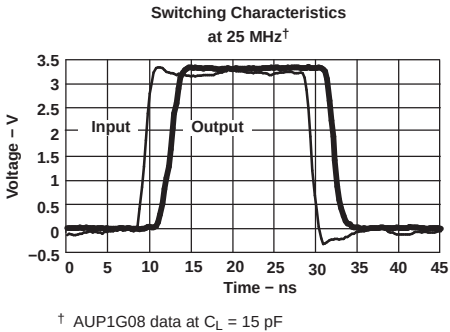


Figure 2. Excellent Signal Integrity

This single 2-input positive-AND gate performs the Boolean function: $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic. NanoStar package technology is a major breakthrough in integrated circuit (IC) packaging concepts, because it uses the die as the package.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

T_A	ORDERABLE PART NUMBER ⁽²⁾	TOP-SIDE MARKING
-40°C to 125°C	SN74AUP1G08QDCKRQ1	SIT

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

FUNCTION TABLE

INPUTS		OUTPUT Y
A	B	
L	L	L
L	H	L
H	L	L
H	H	H

LOGIC DIAGRAM (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	−0.5	4.6	V
V _I	Input voltage range ⁽²⁾	−0.5	4.6	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	−0.5	4.6	V
V _O	Output voltage range in the high or low state ⁽²⁾	−0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		−50 mA
I _{OK}	Output clamp current	V _O < 0		−50 mA
I _O	Continuous output current			±20 mA
	Continuous current through V _{CC} or GND			±50 mA
T _{stg}	Storage temperature range	−65	150	°C
ESD ratings	Human body model (HBM) AEC-Q100 classification level H2			2 kV
	Charged device model (CDM) AEC-Q100 classification level C3B			750 V

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		SN74AUP1G08-Q1	UNIT
		DCK (5 PINS)	
θ _{JA}	Junction-to-ambient thermal resistance	304.7	°C/W
θ _{JCTop}	Junction-to-case (top) thermal resistance	115.3	
θ _{JB}	Junction-to-board thermal resistance	80.3	
ψ _{JT}	Junction-to-top characterization parameter	3.5	
ψ _{JB}	Junction-to-board characterization parameter	79.4	
θ _{JCbot}	Junction-to-case (bottom) thermal resistance	N/A	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

RECOMMENDED OPERATING CONDITIONS			MIN	MAX	UNIT
V _{CC}	Supply voltage		0.8	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}		V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	1.6		
		V _{CC} = 3 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V	0		V
		V _{CC} = 1.1 V to 1.95 V	0.35 × V _{CC}		
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 3 V to 3.6 V	0.9		
V _I	Input voltage		0	3.6	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 0.8 V	−20		μA
		V _{CC} = 1.1 V	−1.1		mA
		V _{CC} = 1.4 V	−1.7		
		V _{CC} = 1.65	−1.9		
		V _{CC} = 2.3 V	−3.1		
		V _{CC} = 3 V	−4		
I _{OL}	Low-level output current	V _{CC} = 0.8 V	20		μA
		V _{CC} = 1.1 V	1.1		mA
		V _{CC} = 1.4 V	1.7		
		V _{CC} = 1.65 V	1.9		
		V _{CC} = 2.3 V	3.1		
		V _{CC} = 3 V	4		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 0.8 V to 3.6 V	200		ns/V
T _A	Operating free-air temperature		−40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

Not recommended operating for air temperature range (unless otherwise noted)										
PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		T _A = 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –20 μA	0.8 V to 3.6 V	V _{CC} – 0.1			V _{CC} – 0.1		V _{CC} – 0.1		V
	I _{OH} = –1.1 mA	1.1 V	0.75 × V _{CC}			0.7 × V _{CC}		0.7 × V _{CC}		
	I _{OH} = –1.7 mA	1.4 V	1.11			1.03		1.03		
	I _{OH} = –1.9 mA	1.65 V	1.32			1.3		1.3		
	I _{OH} = –2.3 mA	2.3 V	2.05			1.97		1.97		
	I _{OH} = –3.1 mA		1.9			1.85		1.85		
	I _{OH} = –2.7 mA	3 V	2.72			2.67		2.67		
	I _{OH} = –4 mA		2.6			2.55		2.55		

ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		T _A = 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OL}	I _{OL} = 20 µA	0.8 V to 3.6 V			0.1		0.1		0.1	V
	I _{OL} = 1.1 mA	1.1 V			0.3 × V _{CC}		0.3 × V _{CC}		0.3 × V _{CC}	
	I _{OL} = 1.7 mA	1.4 V			0.31		0.37		0.37	
	I _{OL} = 1.9 mA	1.65 V			0.31		0.35		0.35	
	I _{OL} = 2.3 mA	2.3 V			0.31		0.33		0.33	
	I _{OL} = 3.1 mA				0.44		0.45		0.45	
	I _{OL} = 2.7 mA	3 V			0.31		0.33		0.33	
	I _{OL} = 4 mA				0.44		0.45		0.45	
I _I	A or B input	V _I = GND to 3.6 V			0.1		0.5		0.5	µA
I _{off}	V _I or V _O = 0 V to 3.6 V	0 V			0.2		0.6		0.8	µA
ΔI _{off}	V _I or V _O = 0 V to 3.6 V	0 V to 0.2 V			0.2		0.6		0.8	µA
I _{CC}	V _I = GND or (V _{CC} to 3.6 V), I _O = 0	0.8 V to 3.6 V			0.5		0.9		1.2	µA
ΔI _{CC}	V _I = V _{CC} – 0.6 V ⁽¹⁾ , I _O = 0	3.3 V			40		50		23	µA
C _i	V _I = V _{CC} or GND	0 V		1.5						pF
		3.6 V		1.5						
C _o	V _O = GND	0 V		3						pF

(1) One input at V_{CC} – 0.6 V, other input at V_{CC} or GND.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A or B	Y	0.8 V		18				ns
			1.2 V ± 0.1 V	2.6	7.3	12.8	2.1	15.6	
			1.5 V ± 0.1 V	1.4	5.2	8.7	0.9	10.3	
			1.8 V ± 0.15 V	1	4.2	6.6	0.5	8.2	
			2.5 V ± 0.2 V	1	3	4.4	0.5	5.5	
			3.3 V ± 0.3 V	1	2.4	3.5	0.5	4.3	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A or B	Y	0.8 V		21				ns
			1.2 V ± 0.1 V	1.5	8.5	14.7	1	17.2	
			1.5 V ± 0.1 V	1	6.2	10	0.5	11.3	
			1.8 V ± 0.15 V	1	5	7.7	0.5	9	
			2.5 V ± 0.2 V	1	3.6	5.2	0.5	6.1	
			3.3 V ± 0.3 V	1	2.9	4.2	0.5	4.7	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 15$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V		24				ns
			1.2 V $\pm$ 0.1 V	3.6	9.9	16.3	3.1	19.9	
			1.5 V $\pm$ 0.1 V	2.3	7.2	11.1	1.8	13.2	
			1.8 V $\pm$ 0.15 V	1.6	5.8	8.7	1.1	10.6	
			2.5 V $\pm$ 0.2 V	1	4.3	5.9	0.5	7.3	
			3.3 V $\pm$ 0.3 V	1	3.4	4.8	0.5	5.9	

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $C_L = 30$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

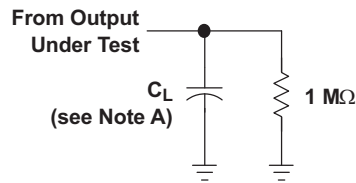
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		$T_A = 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V		32.8						ns
			1.2 V $\pm$ 0.1 V	4.9	13.1	20.9	4.4	25.5	4.4	27.8	
			1.5 V $\pm$ 0.1 V	3.4	9.5	14.2	2.9	16.9	2.9	18	
			1.8 V $\pm$ 0.15 V	2.5	7.7	11	2	13.5	2	19.7	
			2.5 V $\pm$ 0.2 V	1.8	5.7	7.6	1.3	9.4	1.3	11	
			3.3 V $\pm$ 0.3 V	1.5	4.7	6.2	1	7.5	1	8.7	

OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$f = 10$ MHz	0.8 V	4	pF
			1.2 V $\pm$ 0.1 V	4	
			1.5 V $\pm$ 0.1 V	4	
			1.8 V $\pm$ 0.15 V	4	
			2.5 V $\pm$ 0.2 V	4.1	
			3.3 V $\pm$ 0.3 V	4.3	

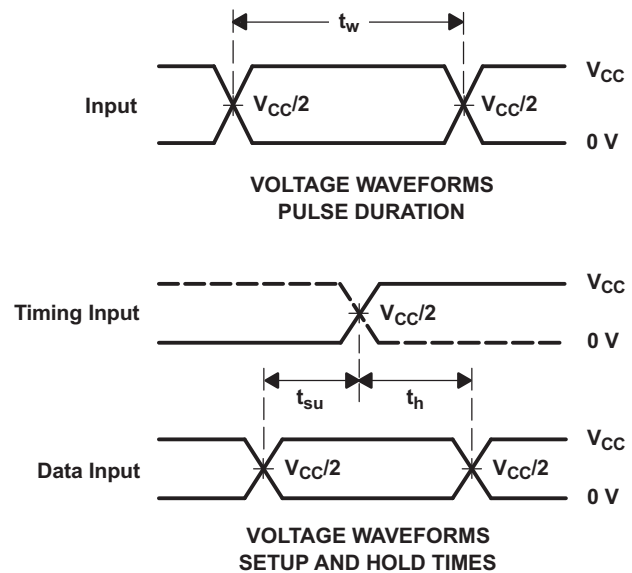
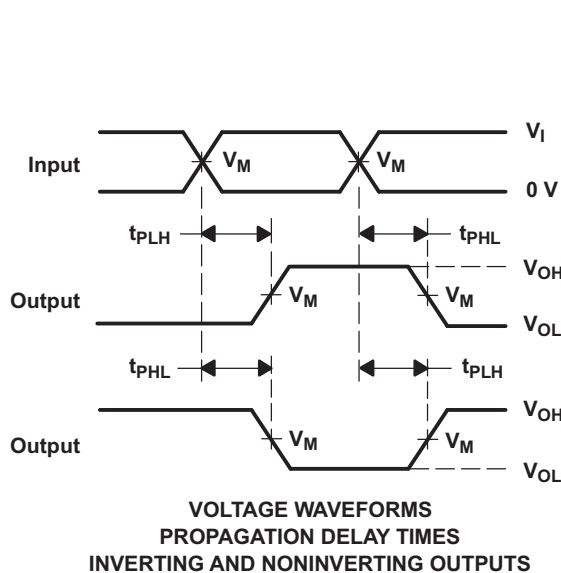
PARAMETER MEASUREMENT INFORMATION (Propagation Delays, Setup and Hold Times, and Pulse Duration)



LOAD CIRCUIT

$T_A = -25^{\circ}\text{C to } 85^{\circ}\text{C}$

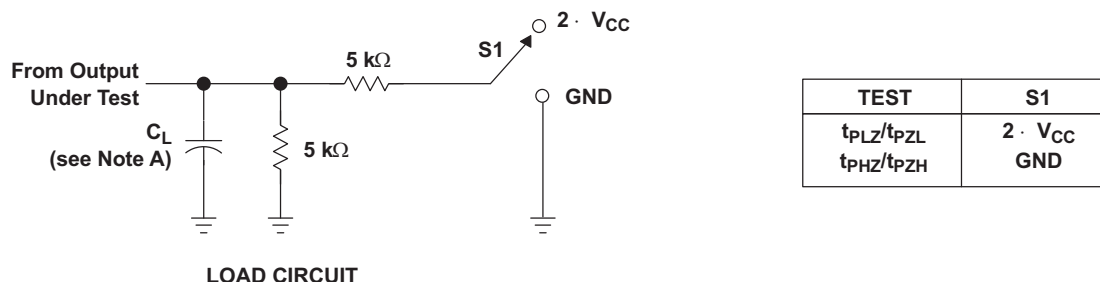
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



- NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: $\text{PRR} \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, slew rate $\geq 1 \text{ V/ns}$.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd} .
E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

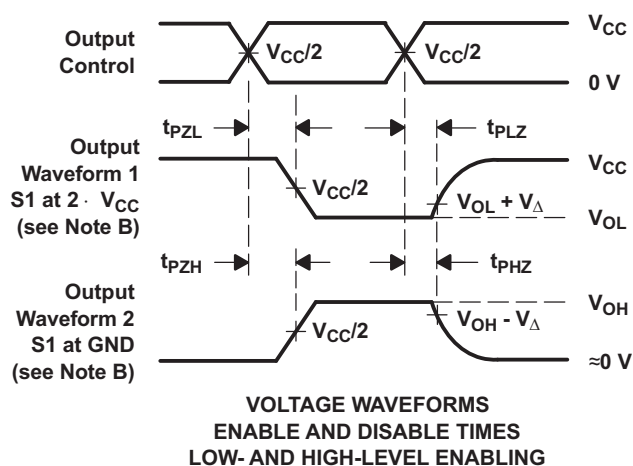
PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



TEST	S1
t_{PLZ}/t_{PZL}	2 · V_{CC}
t_{PHZ}/t_{PHZ}	GND

$T_A = -25^\circ\text{C to } 85^\circ\text{C}$

	$V_{CC} = 0.8\text{ V}$	$V_{CC} = 1.2\text{ V}$ $\pm 0.1\text{ V}$	$V_{CC} = 1.5\text{ V}$ $\pm 0.1\text{ V}$	$V_{CC} = 1.8\text{ V}$ $\pm 0.15\text{ V}$	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$	$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, slew rate $\geq 1\text{ V/ns}$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PHZ} are the same as t_{en} .
 - G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AUP1G08QDCKRQ1	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(SIJ, SIT)
SN74AUP1G08QDCKRQ1.B	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	(SIJ, SIT)

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

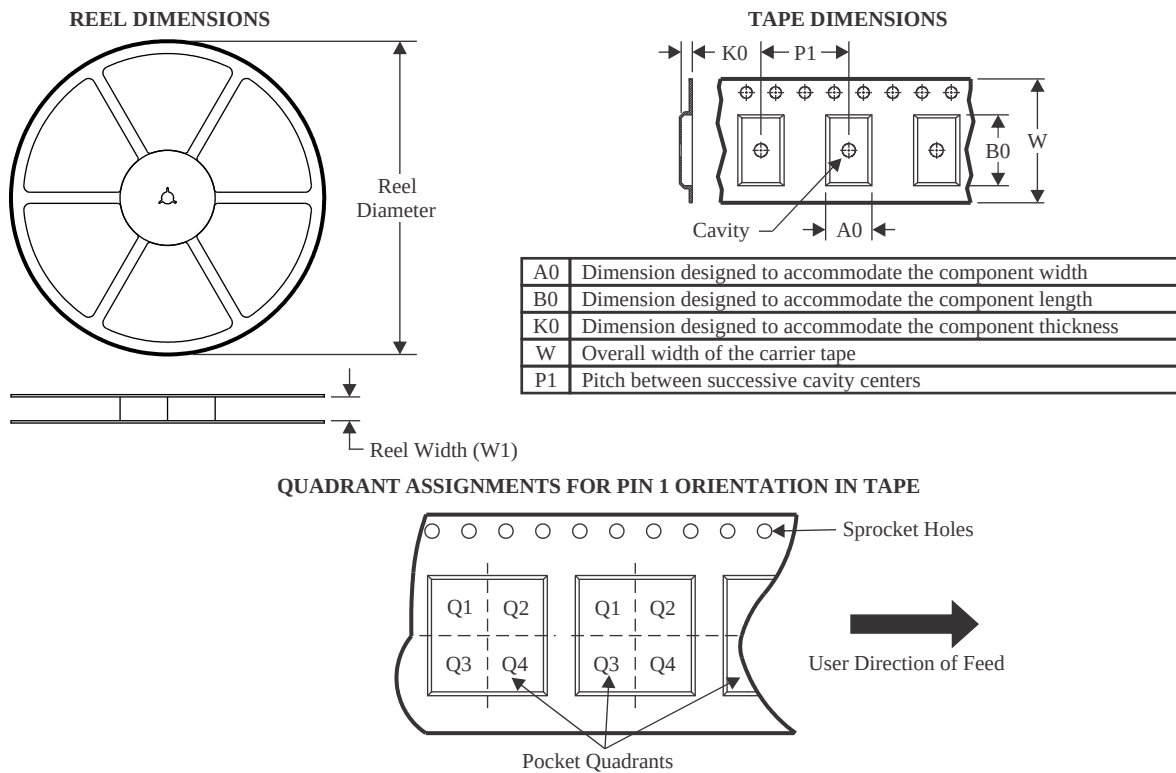
OTHER QUALIFIED VERSIONS OF SN74AUP1G08-Q1 :

- Catalog : [SN74AUP1G08](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

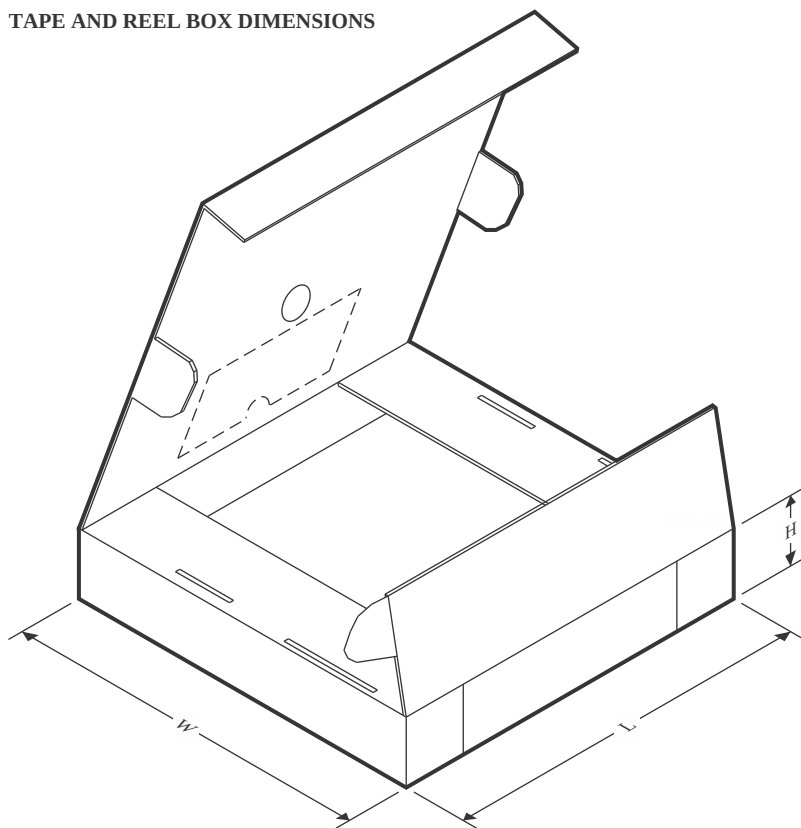
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G08QDCKRQ1	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74AUP1G08QDCKRQ1	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G08QDCKRQ1	SC70	DCK	5	3000	202.0	201.0	28.0
SN74AUP1G08QDCKRQ1	SC70	DCK	5	3000	190.0	190.0	30.0



SOT - 1.1 max height

Technical drawing of a mechanical part showing three views: front, side, and top.

Front View Dimensions:

- Overall width: 2.4 (1.8)
- Overall height: 2.15 (1.85)
- Horizontal hole locations: 1.4 (1.1)
- Vertical hole locations: 1.3 (1.3)
- Hole diameter: 0.15 (0.1)
- Feature **NOTE 4** is indicated.
- Hatched area labeled **PIN 1 INDEX AREA**.

Side View Dimensions:

- Width: 1.1 MAX
- Thickness: 0.1

Top View Dimensions:

- Width: 0.46 TYP
- Height: 0.22 TYP
- Feature **NOTE 5** is indicated.

Feature Control Frames:

- Circular runout: ϕ 0.15
- Surface texture: 0.1
- Feature **NOTE 4** is indicated.
- Feature **NOTE 5** is indicated.

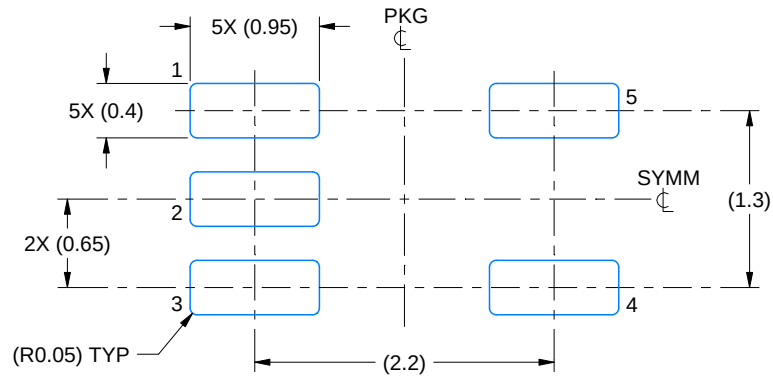
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

EXAMPLE BOARD LAYOUT

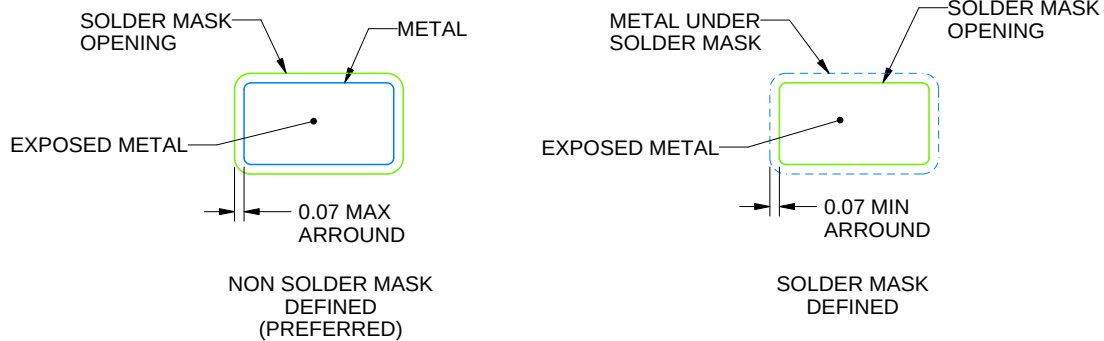
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

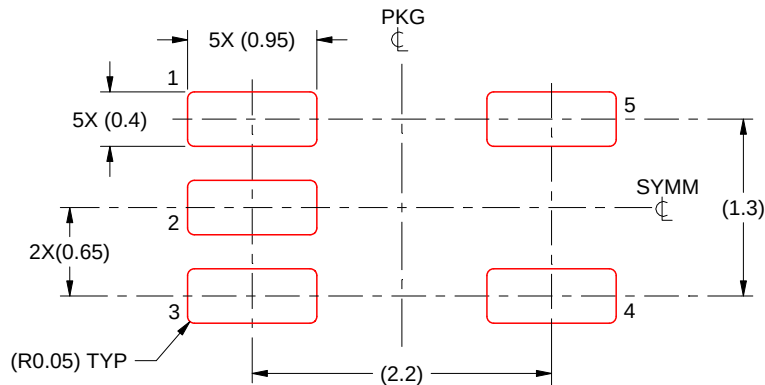


SOLDER MASK DETAILS

4214834/G 11/2024

NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025